



Electrical Specifications:

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Frequency of Operation	Fo		156.250000		MHz	
		Free	quency Stabi	lity		
Frequency Stability	ΔF/F	-20		+20	ppm	Includes calibration tolerance and deviation over operating temperature range
Aging		-5		+5	ppm	1 st year
			RF Output			
Output Type		LV	PECL Compatit	ble		
Output Load		50	Ω to (Vcc-2.0) V	/DC	V	
Symmetry (duty cycle)	Vон	45		55	%	Ref. to 50% of waveform
Logic Level "1"	Vон	Vcc-1.025		Vcc-0.880	V	
Logic Level "0"	T _{DC}	Vcc-1.810		Vcc-1.620	V	
Rise/Fall Time	T _R /T _F			0.4	ns	20% to 80% of waveform
Start-up Time	Tsu			10	ms	T _{ambient} = +25°C
Enable Logic		70% V _{CC} or N/C			V	Pad 1: Output Enabled
Disable Logic				30% Vcc	V	Pad 1: Output Disabled to high-Z
	S	Supply Volta	ge & Power C	onsumptio	n	
Operating Voltage	Vcc	3.135	3.3	3.465	V	
Supply Current	Icc			65	mA	
		Ot	ther Parameter	S		
Phase Jitter (RMS)	ΦJ			0.150	ps	12 kHz to 20 MHz

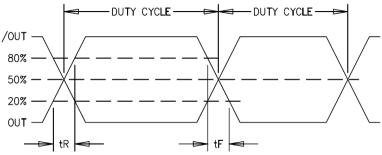




Environmental & Packaging Requirements:

Operating Temperature	TA	-40		+85	°C	
Storage Temperature	Ts	-55		+125	°C	
Mechanical Shock	Per MIL-STD-202, Method 213, Condition C (100 g's, 6 ms duration, 1/2 sinewave)				duration, ½ sinewave)	
Vibration		Per MIL-STD-202, Method 201 & 204 (10 g's from 10-2000 Hz)				
Thermal Cycle	Per MIL-S	Per MIL-STD-883, Method 1010, B (-55°C to 125°C, 15 min. dwell, 10 cycles)				
Hermeticity	Per MIL-S	Per MIL-STD-202, Method 112 (1 x 10 ⁻⁸ atm cc/s of Helium)				
Moisture Sensitivity	MSL 1					
Level (MSL)						
Solderability	Per EIAJ-STD-002					
Max. Soldering	See solder profile, Figure 1					
Conditions						
Package Type	3.20 mm (typ) X 5.00 mm (typ) X 1.40 (max) mm 6-pad leadless ceramic. RoHS compliant.					

Output Waveform:



Marking, Pin Out:

Pad	Function
1	Enable/Disable
2	N/C
3	Ground
4	Output
5	Complementary Output
6	+V _{cc}

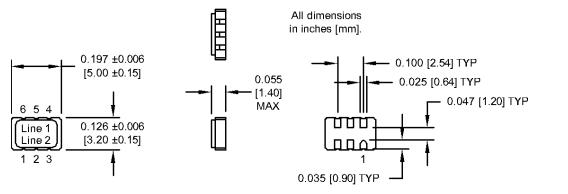
Part Marking		
Line 1	156M250	
Line 2	M yywwvv	

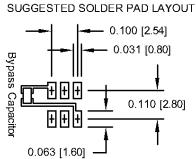
	Legend			
уу	Year			
ww	Work Week			
vv	Factory Code			



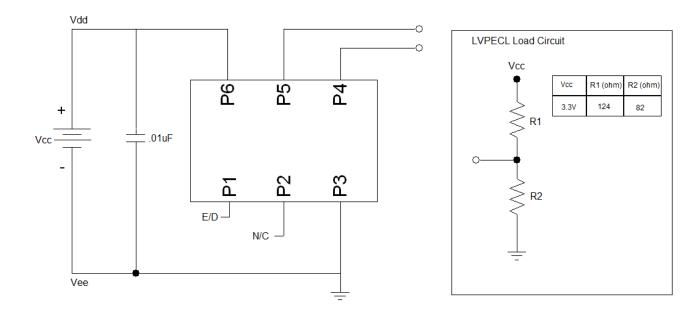


Dimensions:





Typical Test Circuit & Load Circuit Diagrams:

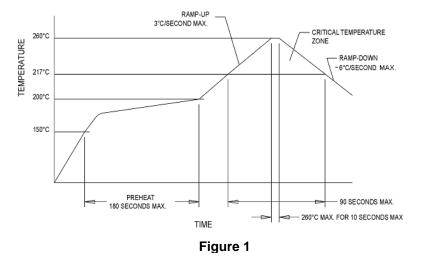


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Soldering Conditions:



Datasheet Revision Table:

Date	Rev.	Author	Details of Revision		
06/21/18	0	DCO	Original release		
06/29/18	А	MM	Updated Phase jitter specification.		